# DISCRETE SEMICONDUCTORS

# DATA SHEET

# **BT300S series**Thyristors

**Product specification** 

September 1997



# **Thyristors**

BT300S series

BT300M series

## **GENERAL DESCRIPTION**

Glass passivated thyristors in a plastic envelope, suitable for surface mounting, intended for use in applications high requiring bidirectional blocking voltage capability and high thermal cycling performance. Typical applications include motor control, industrial and domestic lighting, heating and static switching.

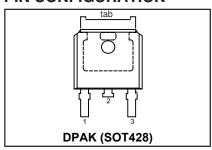
## **QUICK REFERENCE DATA**

SYMBOL	PARAMETER	MAX.	MAX.	MAX.	UNIT
V <sub>DRM</sub> ,	BT300S (or BT300M)- Repetitive peak off-state voltages	<b>500R</b> 500	<b>600R</b> 600	<b>800R</b> 800	V
I <sub>T(AV)</sub> I <sub>T(RMS)</sub> I <sub>TSM</sub>	Average on-state current RMS on-state current Non-repetitive peak on-state current	5 8 65	5 8 65	5 8 65	A A A

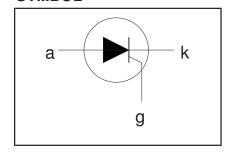
## **PINNING - SOT428**

PIN NUMBER	Standard S	Alternative M
1	cathode	gate
2	anode	anode
3	gate	cathode
tab	anode	anode

# **PIN CONFIGURATION**



# **SYMBOL**



## **LIMITING VALUES**

Limiting values in accordance with the Absolute Maximum System (IEC 134).

SYMBOL	PARAMETER	CONDITIONS	MIN.		MAX.		UNIT
V <sub>DRM</sub> , V <sub>RRM</sub>	Repetitive peak off-state voltages		-	<b>-500R</b> 500 <sup>1</sup>	<b>-600R</b> 600 <sup>1</sup>	<b>-800R</b> 800	V
I <sub>T(AV)</sub> I <sub>T(RMS)</sub> I <sub>TSM</sub>	Average on-state current RMS on-state current Non-repetitive peak on-state current	half sine wave; $T_{mb} \le 107$ °C all conduction angles half sine wave; $T_j = 25$ °C prior to surge	- -		5 8		A A
	on state demont	t = 10 ms t = 8.3 ms	-		65 71		A A
l <sup>2</sup> t	I <sup>2</sup> t for fusing	t = 10 ms	-		21		A <sup>2</sup> s
dl <sub>T</sub> /dt	Repetitive rate of rise of on-state current after triggering	$I_{TM} = 10 \text{ A}; I_G = 50 \text{ mA}; $ $dI_G/dt = 50 \text{ mA/}\mu\text{s}$	-		50		A/μs
I <sub>GM</sub>	Peak gate current		-		2		Α
V <sub>GM</sub>	Peak gate voltage		-		5		V
V <sub>RGM</sub> P <sub>GM</sub>	Peak reverse gate voltage Peak gate power		_		5 5		l w l
P <sub>G(AV)</sub>	Average gate power	over any 20 ms period	_		0.5		w
T <sub>stg</sub>	Storage temperature Operating junction temperature	police	-40 -		150 125		ů, Ö

September 1997 1 Rev 1.200

<sup>1</sup> Although not recommended, off-state voltages up to 800V may be applied without damage, but the thyristor may switch to the on-state. The rate of rise of current should not exceed 15  $A/\mu s$ .

**Thyristors** 

BT300S series BT300M series

# THERMAL RESISTANCES

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
R <sub>th j-mb</sub>	Thermal resistance		-	-	2.2	K/W
R <sub>th j-a</sub>	junction to mounting base Thermal resistance junction to ambient	pcb (FR4) mounted; footprint as in Fig.14	-	75	-	K/W

# STATIC CHARACTERISTICS

T<sub>i</sub> = 25 °C unless otherwise stated

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
I <sub>GT</sub>	Gate trigger current	$V_D = 12 \text{ V}; I_T = 0.1 \text{ A}$	-	2	15	mA
l I <sub>L</sub>	Latching current	$V_D^2 = 12 \text{ V}; I_{GT}^2 = 0.1 \text{ A}$	-	10	40	mA
l i <sub>H</sub>	Holding current	$V_{\rm D} = 12 \text{ V}; I_{\rm GT} = 0.1 \text{ A}$	-	10	20	mA
ĺΫ́	On-state voltage	$I_{T} = 12 \text{ A}$	-	1.35	1.6	V
V <sub>GT</sub>	Gate trigger voltage	$\dot{V}_{D} = 12 \text{ V}; I_{T} = 0.1 \text{ A}$	-	0.6	1.5	V
		$V_D = V_{DRM(max)}$ ; $I_T = 0.1 \text{ A}$ ; $T_i = 125 ^{\circ}\text{C}$	0.25	0.4	-	V
I <sub>D</sub> , I <sub>R</sub>	Off-state leakage current	$V_D = V_{DRM(max)}^{Station}$ ; $V_R = V_{RRM(max)}$ ; $V_i = 125  ^{\circ}C$	-	0.1	0.5	mA

# **DYNAMIC CHARACTERISTICS**

 $T_i = 25$  °C unless otherwise stated

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
dV <sub>D</sub> /dt	Critical rate of rise of off-state voltage	$\begin{aligned} V_{\text{DM}} &= 67\% \ V_{\text{DRM(max)}}; \ T_j = 125 \ ^{\circ}\text{C}; \\ \text{exponential waveform.} \\ &\qquad \qquad \text{Gate open circuit} \\ &\qquad \qquad R_{\text{GK}} = 100 \ \Omega \end{aligned}$	50 200	100 1000		V/μs V/μs
t <sub>gt</sub>	Gate controlled turn-on time Circuit commutated	$ \begin{aligned} &I_{TM} = 10 \text{ A; } V_D = V_{DRM(max)}; \ I_G = \widetilde{0}.1 \text{ A; } \\ &dI_G/dt = 5 \text{ A/}\mu s \\ &V_D = 67\% \ V_{DRM(max)}; \ T_j = 125 \ ^{\circ}C; \\ &I_{TM} = 12 \text{ A; } V_B = 25 \text{ V; } dI_{TM}/dt = 30 \text{ A/}\mu s; \end{aligned} $	-	2 70	-	μs μs
ч	turn-off time	$I_{TM} = 12 \text{ A}; V_R = 25 \text{ V}; dI_{TM}/dt = 30 \text{ A/}\mu\text{s}; dV_D/dt = 50 \text{ V/}\mu\text{s}; R_{GK} = 100 \Omega$				·

# **Thyristors**

BT300S series BT300M series

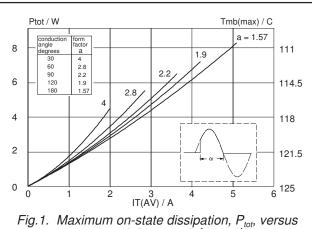


Fig.1. Maximum on-state dissipation,  $P_{tot}$ , versus average on-state current,  $I_{T(AV)}$ , where  $a = form \ factor = I_{T(RMS)} / I_{T(AV)}$ .

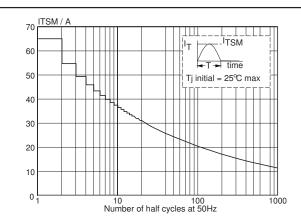


Fig.4. Maximum permissible non-repetitive peak on-state current  $I_{TSM}$ , versus number of cycles, for sinusoidal currents, f = 50 Hz.

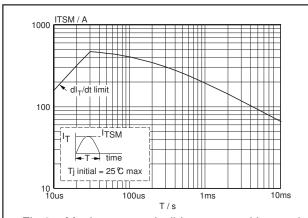


Fig.2. Maximum permissible non-repetitive peak on-state current  $I_{TSM}$ , versus pulse width  $t_p$ , for sinusoidal currents,  $t_p \le 10$ ms.

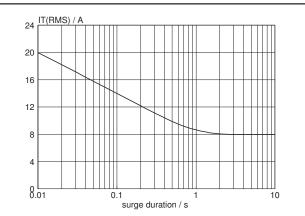


Fig.5. Maximum permissible repetitive rms on-state current  $I_{T(RMS)}$ , versus surge duration, for sinusoidal currents, f = 50 Hz;  $T_{mb} \le 107 ^{\circ}\text{C}$ .

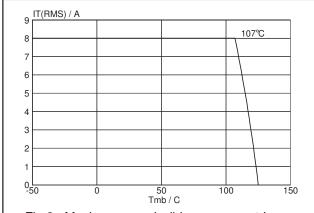
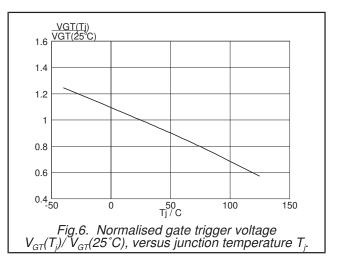
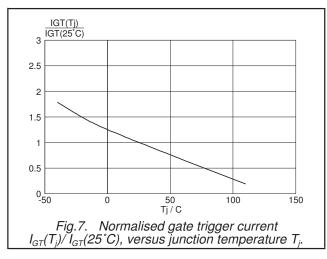


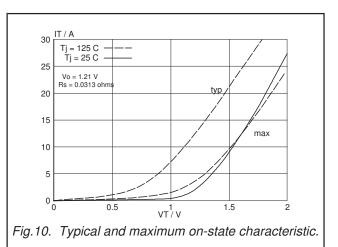
Fig.3. Maximum permissible rms current  $I_{T(RMS)}$ , versus mounting base temperature  $T_{mb}$ .

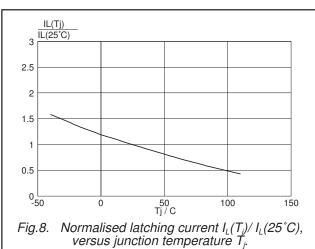


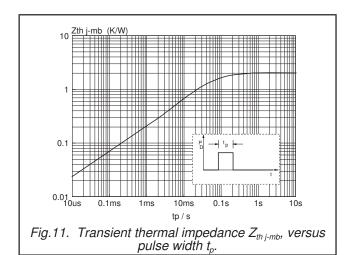
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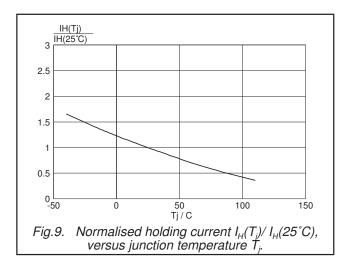
BT300S series BT300M series

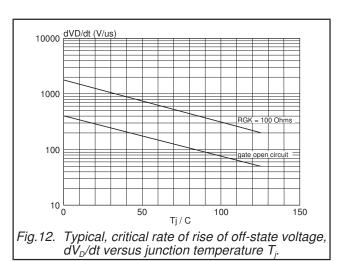








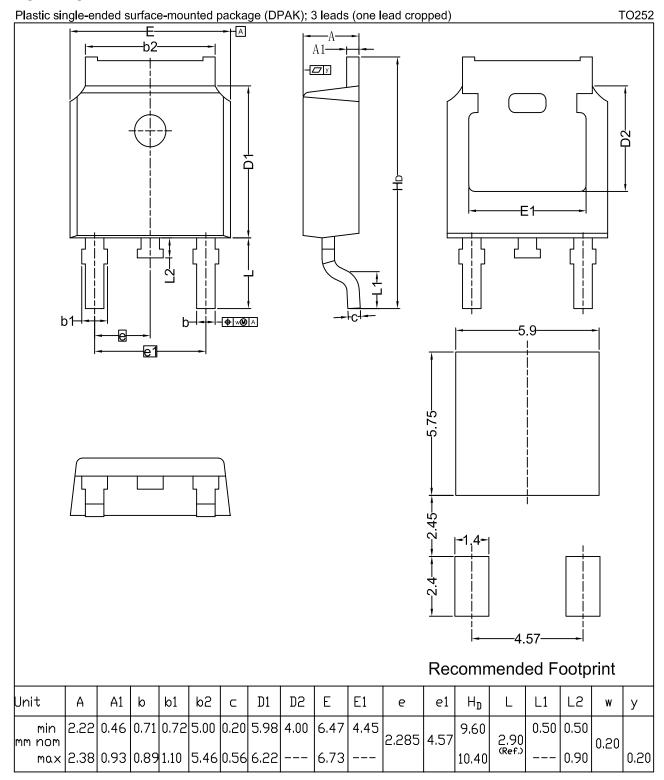




**Thyristors** 

BT300S series BT300M series

# **MECHANICAL DATA**



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Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
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